

FORM PTO-1449

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE

ATTORNEY DOCKET NO.

300.1138

APPLICATION NO.

10/706912

## LIST OF REFERENCES CITED BY APPLICANT

(Use several sheets if necessary)

FIRST NAMED INVENTOR

Mitsutoshi HIGASHI

FILING DATE

November 14, 2003

GROUP ART UNIT

2813

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NO.	DATE	NAME	CLASS	SUB- CLASS	FILING DATE
<i>Sh</i>	AA	2002/00018 73 A1	01/2002	Kang	—	—	
	AB						
	AC						
	AD						
	AE						
	AF						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB- CLASS	TRANSLATION YES NO	
<i>Sh</i>	AG	8-184608	07/1996	Japan			abs	
<i>Sh</i>	AH	2002-43463	02/2002	Japan				X
	AI							
	AJ							
	AK							
	AL							

## OTHER REFERENCES (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

	AM	
	AN	
	AO	

EXAMINER

*Harriet Schuly*

DATE CONSIDERED

2/27/06

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



Sheet 1 of 1

FORM PTO-1449  U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE  <b>INFORMATION DISCLOSURE STATEMENT</b>  (Use several sheets if necessary)	ATTORNEY DOCKET NO. 300.1138	APPLICATION NO. 10/706,912
	FIRST NAMED INVENTOR Mitsutoshi HIGASHI	
	FILING DATE November 14, 2003	GROUP ART UNIT

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NO.	DATE	NAME	CLASS	SUB- CLASS	FILING DATE
<i>Sh</i>	AA	6,214,644	04/10/01	GLENN	<u>          </u>	<u>          </u>	
<i>Sh</i>	AB	5,610,431	03/11/97	MARTIN	<u>          </u>	<u>          </u>	
<i>Sh</i>	AC	6,316,840	11/13/01	OTANI	<u>          </u>	<u>          </u>	
<i>Sh</i>	AD	5,895,233	04/20/99	HIGASHI et al.	<u>          </u>	<u>          </u>	
	AE						
	AF						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NO.	DATE	COUNTRY	TRANSLATION YES NO	ABSTRACT
<i>Sh</i>	AG	99/67818	12/29/99	WIPO	<u>          </u>	X
<i>Sh</i>	AH	02/055431	07/18/02	WIPO	<u>          </u>	X
	AI					
	AJ					

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

TRANSLATION  
YES NO

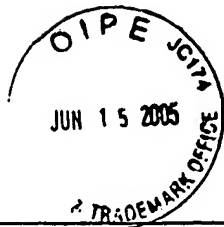
<i>Sh</i>	AK	G. A. Riley, "Stud Bump Flip Chip Assembly of MEMS and MOEMS," Proceedings of the SPIE, International Symposium on Microelectronics, October 2001, vol. 4587, pp. 662-665.		
<i>Sh</i>	AL	H. Park et al., "Packaging of the RF-MEMS Switch," Design Characterization, and Packaging for MEMS and Microelectronics II, December 2001, Proceedings of SPIE, vol. 4593, pp. 234-243.		
<i>Sh</i>	AM	J. Kim et al., "Ultrasonic Bonding of In/Au and Al/Al for Hermetic Sealing of MEMS Packaging," MEMS 2002, IEEE International Micro Electro Mechanical Systems Conference, Proceedings of the IEEE, January 2002, pp. 415-418.		

EXAMINER

DATE CONSIDERED

*Wesley Schely**2/27/06*

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# ATTACHMENT 1(g)

<b>LIST OF ADDITIONAL SUBMITTED DOCUMENTS</b>	ATTORNEY DOCKET NO.	APPLICATION NO.
	300.1138	10/706,912
	FIRST NAMED INVENTOR	
	Mitsutoshi HIGASHI	
	FILING DATE	GROUP ART UNIT
	November 14, 2003	

The following document(s) is/are listed in accordance with the duty of disclosure provisions of 37 CFR § 1.56, so that the Examiner may consider same should he deem any thereof to be material to examination of the subject application.

It is requested that the Examiner acknowledge his consideration of document(s) below-listed by initialing same in the space provided adjacent each such application and that the Examiner sign and date this form at the bottom thereof to confirm such consideration having been given.

This submission in no way represents an admission that any of the information listed herein constitutes prior art with respect to the subject application; and unless and until such prior art status is established, this submission is not a request that the information presented herein be printed on the face of any patent issuing from the subject application in which this information is being filed.

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NO.	DATE	NAME	CLASS	SUB-CLASS	FILING DATE
	AA						
	AB						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION YES NO	
	AC							
	AD							

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

TRANSLATION YES NO	
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	AE	Partial European Search Report dated May 9, 2005 of Application No. EP 03 25 7126.		
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EXAMINER	DATE CONSIDERED
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10/706,912

FIRST NAMED INVENTOR

Mitsutoshi HIGASHI

FILING DATE

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GROUP PART UNIT

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## INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

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<i>Sh</i>	AA	5,895,233	04/20/99	HIGASHI et al.			
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<i>J</i>	AC	5,610,431	03/11/97	MARTIN			
<i>J</i>	AD	6,214,644	04/10/01	GLENN			
<i>J</i>	AE	6,384,473	05/07/02	PETERSON et al.			
<i>Sh</i>	AF	6,140,144	10/31/00	NAJAFI et al.			

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<i>Sh</i>	AG	02/01633	01/03/02	WIPO		
<i>J</i>	AH	99/67818	12/29/99	WIPO		
<i>Sh</i>	AI	02/055431	07/18/02	WIPO		

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TRANSLATION  
YES NO

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<i>J</i>	AK	K. Jongbaeg et al., "Ultrasonic Bonding of In/Au and Aval for Hermetic Sealing of MEMS Packaging," IEEE International Micro Electro Mechanical Systems Conference, Proceedings of the IEEE, January 2002, pp. 415-418.		
<i>J</i>	AL	M. Heschel, "Stacking Technology for a Space Constrained Microsystem," Micro Electro Mechanical Systems, 1998, MEMS 98, Proceedings, IEEE, January 1998, pp. 312-317.		
<i>Sh</i>	AM	H. Park et al., "Packaging of the RF-MEMS Switch," Design, Characterization and Packaging for MEMS and Microelectronics II, Proceedings of the SPIE, vol. 4593, December 2001, pp. 234-243.		

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*Naama Schuly**2/27/06*

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FIRST NAMED INVENTOR Mitsutoshi HIGASHI	
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		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB- CLASS	TRANSLATION YES NO	
	AC							

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

			TRANSLATION YES NO	
	AD	European Search Report and Annex of Application No. EP 03 25 7126 dated July 20, 2005.		
	AE	Partial European Search Report and Annex of Application No. EP 03 25 7126 dated May 9, 2005.		

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